

C09G

POLISHING COMPOSITIONS (French polish [C09F 11/00](#)); SKI WAXES

Definition statement

This place covers:

- Polishing compositions containing abrasives or grinding agents as well as polishing compositions based on aqueous dispersions, such as chemical mechanical polishing slurries for polishing semi conductors.
- Polishing compositions based on wax -this includes compositions based on mixtures of wax and natural or synthetic resins- and polishing compositions based on non-waxy substances, e. g. natural or synthetic resins.
- Ski waxes

References

Limiting references

This place does not cover:

Coating compositions based on oil, fats or waxes or derivatives thereof	C09D 191/00
Coating compositions based on natural resins or derivatives thereof	C09D 193/00
French polish	C09F 11/00
Detergents	C11D
Cleaning compositions for semi conductor devices	H01L 21/02041

Informative references

Attention is drawn to the following places, which may be of interest for search:

Grinding; Polishing machines and processes	B24B
Compositions of macromolecular compounds	C08L
Compositions of oils, fats or waxes or derivatives thereof	C08L 91/00
Compositions of natural resins or derivatives thereof	C08L 93/00
Abrasive powders, suspension and pastes for polishing	C09K 3/1454
Chemical polishing of metals	C23F
Cleaning or de-greasing of metallic material by chemical methods	C23G
Mirror polishing of wafers	H01L 21/02024
Manufacture of semiconductor devices, polishing	H01L 21/304
Manufacture of semiconductor devices, chemical mechanical polishing	H01L 21/30625
Manufacture of semiconductor devices, planarisation of the insulating layers	H01L 21/31051
Manufacture of semiconductor devices, deposition of non-insulating layers on insulating layers, chemical mechanical polishing thereof	H01L 21/3212
Manufacture of semiconductor devices, planarisation of conductors	H01L 21/7684

Synonyms and Keywords

In patent documents, the following abbreviations are often used:

CMP	Chemical Mechanical Polishing
-----	-------------------------------

C09G 1/00

Polishing compositions (French polish [C09F 11/00](#); detergents [C11D](#))

Definition statement

This place covers:

Polishing compositions containing abrasives or grinding agents; aqueous compositions and other polishing compositions based on wax or on non-waxy substances.

References

Limiting references

This place does not cover:

French polish	C09F 11/00
Abrasives as such	C09K 3/14
Detergents	C11D

Informative references

Attention is drawn to the following places, which may be of interest for search:

Abrasive powders, suspension and pastes for polishing	C09K 3/1463
Manufacture of semiconductor devices, polishing	H01L 21/304
Manufacture of semiconductor devices, chemical mechanical polishing	H01L 21/30625
Manufacture of semiconductor devices, dielectric removal step	H01L 21/31053
Manufacture of semiconductor devices, deposition of non-insulating layers on insulating layers, chemical mechanical polishing thereof	H01L 21/3212
Manufacture of semiconductor devices, planarisation of conductors	H01L 21/7684

Special rules of classification

Abrasive free Chemical Mechanical Polishing (CMP) compositions are classified in [C09G 1/04](#). All other CMP compositions are classified in [C09G 1/02](#).

Glossary of terms

In this place, the following terms or expressions are used with the meaning indicated:

CMP	Chemical Mechanical Polishing
-----	-------------------------------

C09G 3/00

Ski waxes

Definition statement

This place covers:

Ski waxes.

References

Informative references

Attention is drawn to the following places, which may be of interest for search:

Apparatus for waxing or dewaxing	A63C 11/08
----------------------------------	----------------------------